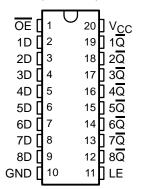
SCLS145C - DECEMBER 1982 - REVISED MARCH 2003

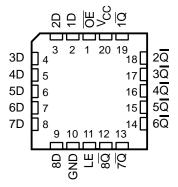
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Drive Bus Lines Directly or Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}

SN54HC563...J OR W PACKAGE SN74HC563...DW OR N PACKAGE (TOP VIEW)



- Typical t_{pd} = 21 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Bus-Structured Pinout

SN54HC563 . . . FK PACKAGE (TOP VIEW)



description/ordering information

These 8-bit transparent D-type latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

While the latch-enable (LE) input is high, the \overline{Q} outputs follow the complements of the data (D) inputs. When LE is taken low, the outputs are latched at the inverses of the levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased high logic level provide the capability to drive bus lines without interface or pullup components.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

OE does not affect internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

ORDERING INFORMATION

TA	PACKAC	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74HC563N	SN74HC563N
–40°C to 85°C	SOIC - DW	Tube	SN74HC563DW	HC563
	301C - DW	Tape and reel	SN74HC563DWR	псэвэ
	CDIP – J	Tube	SNJ54HC563J	SNJ54HC563J
–55°C to 125°C	CFP – W	Tube	SNJ54HC563W	SNJ54HC563W
	LCCC – FK	Tube	SNJ54HC563FK	SNJ54HC563FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

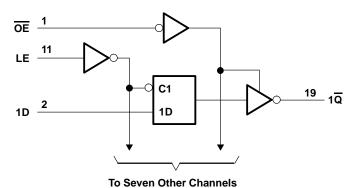


SCLS145C - DECEMBER 1982 - REVISED MARCH 2003

FUNCTION TABLE (each latch)

	INPUTS	OUTPUT	
OE	LE	D	Q
L	Н	Н	L
L	Н	L	Н
L	L	Χ	\overline{Q}_0
Н	X	X	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC}) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package	58°C/W
N package	69°C/W
Storage temperature range, T _{sto}	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



SCLS145C - DECEMBER 1982 - REVISED MARCH 2003

recommended operating conditions (see Note 3)

			SN	154HC56	3	SN	174HC56	3	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
VCC	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
٧ıH	High-level input voltage	V _{CC} = 4.5 V	3.15		ςh	3.15			V
		V _{CC} = 6 V	4.2	FL	,	4.2			
		V _{CC} = 2 V		2	0.5			0.5	
٧ _{IL}	Low-level input voltage	V _{CC} = 4.5 V		Ç)	1.35			1.35	V
		V _{CC} = 6 V	4	Ž	1.8			1.8	
٧ _I	Input voltage		0		VCC	0		VCC	V
۷o	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
t _t	Input transition (rise and fall) time	V _{CC} = 4.5 V			500			500	ns
		V _{CC} = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CO	ONDITIONS	Vaa	Т	A = 25°C	;	SN54F	IC563	SN74H	C563	UNIT
PARAMETER	1251 CC	CNDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4	V	4.4		
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9	Vie	5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7	PRE	3.84		
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2	1 6	5.34		
			2 V		0.002	0.1	22	0.1		0.1	
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1	70	0.1		0.1	
VOL	$V_I = V_{IH}$ or V_{IL}		6 V		0.001	0.1	d	0.1		0.1	V
		$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
loz	$V_O = V_{CC}$ or 0		6 V		±0.01	±0.5		±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

SN54HC563, SN74HC563 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCLS145C - DECEMBER 1982 - REVISED MARCH 2003

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V	T _A = :	25°C	SN54H	IC563	SN74H	IC563	UNIT
		vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNII
		2 V	80		120	4	100		
t _W	Pulse duration, LE high	4.5 V	16		24	EW	20		ns
		6 V	14		20	FV	17		
		2 V	50		75	DA.	63		
t _{su}	Setup time, data before LE↓	4.5 V	10		15		13		ns
		6 V	9		13		11		
		2 V	5		% 5		5		
t _h	Hold time, data after LE \downarrow	4.5 V	5		5		5		ns
		6 V	5		5		5		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	Vaa	T	λ = 25°C	;	SN54F	IC563	SN74H	C563	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V		77	175		265		220		
	D	Q	4.5 V		26	35		53		44		
			6 V		23	30		45		37	no	
^t pd			2 V		90	175		265		220	ns	
	LE	Any \overline{Q}	4.5 V		27	35		53		44		
			6 V		23	30	2	45		37		
			2 V		70	150	70	225		190		
t _{en}	ŌĒ	Any Q	Any Q	4.5 V		24	30	0	45		38	ns
			6 V		21	26		38		32		
			2 V		47	150		225		190		
^t dis	ŌĒ	Any Q	4.5 V		23	30		45		38	ns	
			6 V		21	26		38		32		
			2 V		28	60		90		75	_	
t _t	t _t		4.5 V		8	12		18		15	ns	
			6 V		6	10		15		13		

SN54HC563, SN74HC563 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCLS145C - DECEMBER 1982 - REVISED MARCH 2003

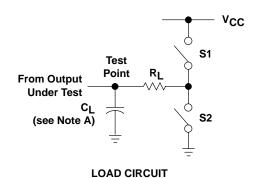
switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

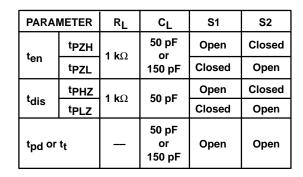
PARAMETER	FROM	то	V	T,	չ = 25°C	;	SN54H	C563	SN74H	C563	UNIT																								
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII																								
			2 V		95	200		300		250																									
	D	Q	4.5 V		33	40		60		50																									
. .			6 V		29	34		51		43																									
^t pd		Any Q	2 V		103	225		335		285	ns																								
	LE		4.5 V		33	45		67		57																									
			6 V		29	38	2	57		48																									
			2 V		85	200	70	300		250																									
t _{en}	ŌĒ	Any Q	4.5 V		29	40	9	60		50	ns																								
			6 V		26	34		51		43																									
			2 V		60	210		315		265																									
t _t	Any Q	Any Q	Any Q	Any \overline{Q}	Any Q	Any Q	Any Q	Any $\overline{\mathbb{Q}}$	Any Q	4.5 V		17	42		63		53	ns																	
			6 V		14	36		53		45																									

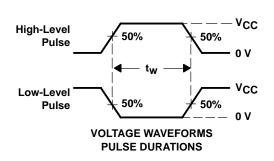
operating characteristics, $T_A = 25^{\circ}C$

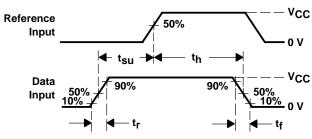
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per latch	No load	50	pF

PARAMETER MEASUREMENT INFORMATION

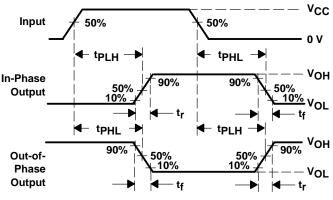


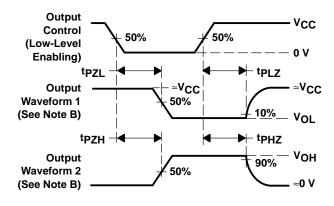






VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

www.ti.com

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC563DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC563	Samples
SN74HC563DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC563	Samples
SN74HC563N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC563N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



PACKAGE OPTION ADDENDUM

10-Dec-2020

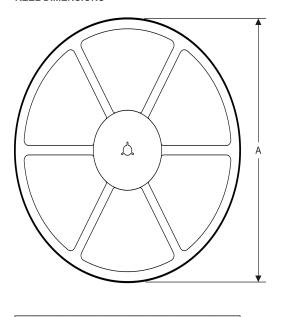
In no event shall TI's liabilit	y arising out of such information	exceed the total purchase	price of the TI part(s) a	at issue in this document sold by	TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

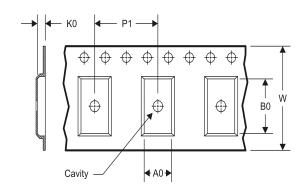
www.ti.com 14-Jul-2012

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC563DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

www.ti.com 14-Jul-2012



*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	SN74HC563DWR	SOIC	DW	20	2000	367.0	367.0	45.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

Tl's products are provided subject to Tl's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such Tl products. Tl's provision of these resources does not expand or otherwise alter Tl's applicable warranties or warranty disclaimers for Tl products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2020, Texas Instruments Incorporated